

Abstract of the Disclosure

A stack type multi-chip package with an increased reliability is provided. The stack type multi-chip package comprises a first semiconductor chip which shows good results when tested for reliability after being assembled at the package level, at least one second semiconductor chip which is in the wafer level and is stacked on the first semiconductor chip via stacking means, a first connecting unit for electrically connecting the first semiconductor chip to an external system, and a second connecting unit for electrically connecting the second semiconductor chip to the external system. The first connecting unit is different from the second connecting unit. Since the stack type multi-chip package comprises the semiconductor chip which shows good results when tested for reliability after being assembled at the package level, the reliability of the stack type multi-chip package can be effectively increased.

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